



Shantou Huashan Electronic Devices Co.,Ltd.

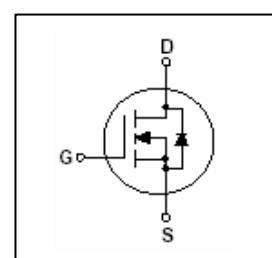
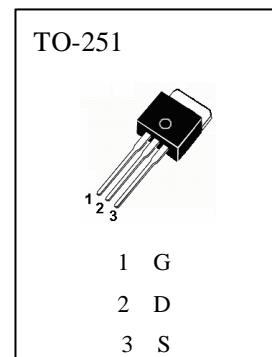
N-Channel MOSFET

**HFU1N60****APPLICATIONS**

high-Speed Switching.

**ABSOLUTE MAXIMUM RATINGS (  $T_a=25$  )**

$T_{stg}$ —— Storage Temperature.....	-55~150
$T_j$ —— Operating Junction Temperature .....	150
$P_D$ —— Allowable Power Dissipation ( $T_c=25$ ) .....	28W
$V_{DSS}$ —— Drain-Source Voltage .....	600V
$V_{GSS}$ —— Gate-Source Voltage .....	$\pm 30V$
$I_D$ —— Drain Current ( $T_c=25$ ) .....	1A
$I_{DM}$ —— Drain Current ( Pulsed ) .....	4A

**ELECTRICAL CHARACTERISTICS (  $T_a=25$  )**

Symbol	Characteristics	Min	Typ	Max	Unit	Test Conditions
$BV_{DSS}$	Drain-Source Breakdown Voltage	600			V	$I_D=250 \mu A, V_{GS}=0V$
$I_{DSS}$	Zero Gate Voltage Drain Current			1	$\mu A$	$V_{DS}=600V, V_{GS}=0$
$I_{GSS}$	Gate –Source Leakage Current			$\pm 100$	nA	$V_{GS}=\pm 30V, V_{DS}=0V$
$V_{GS(th)}$	Gate Threshold Voltage	2.5		4.5	V	$V_{DS}=V_{GS}, I_D=250 \mu A$
$R_{DS(on)}$	Static Drain-Source On-Resistance		9.3	11.5	?	$V_{GS}=10V, I_D=0.5A$
$g_{FS}$	Forward Transconductance		0.75		S	$V_{DS}=40V, I_D=0.5A^*$
$C_{iss}$	Input Capacitance	130	170		pF	$V_{DS}=25V, V_{GS}=0, f=1MHz$
$C_{oss}$	Output Capacitance	19	25		pF	
$C_{rss}$	Reverse Transfer Capacitance	3.5	4.5		pF	
$t_{d(on)}$	Turn - On Delay Time	7	24		nS	$V_{DD}=300V, I_D=1.1A$ $R_G=25 \Omega^*$
$tr$	Rise Time	21	52		nS	
$t_{d(off)}$	Turn - Off Delay Time	13	36		nS	
$t_f$	Fall Time	27	64		nS	$V_{DS}=480V, I_D=1.1A$ $V_{GS}=10V^*$
$Q_g$	Total Gate Charge	4.8	6.2		nC	
$Q_{gs}$	Gate–Source Charge	0.7			nC	
$Q_{gd}$	Gate–Drain Charge	2.7			nC	$I_S=0.5A, V_{GS}=0$
$I_s$	Continuous Source Current			1	A	
$V_{SD}$	Diode Forward Voltage			1.4	V	
$R_{th(j-c)}$	Thermal Resistance , Junction-to-Case			4.53	/W	

\*Pulse Test : Pulse Width 300  $\mu s$ , Duty Cycle 2%



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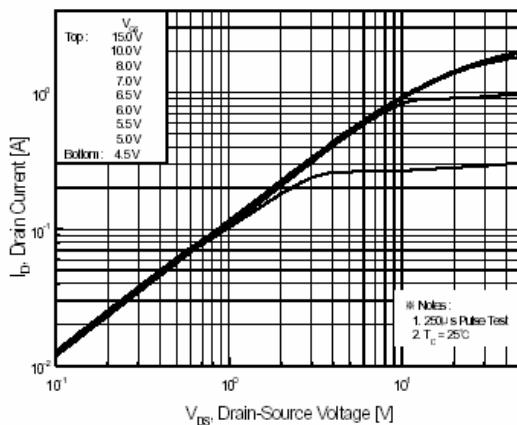


Figure 1. On-Region Characteristics

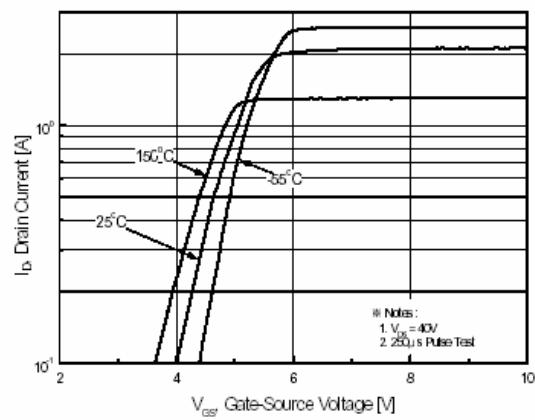


Figure 2. Transfer Characteristics

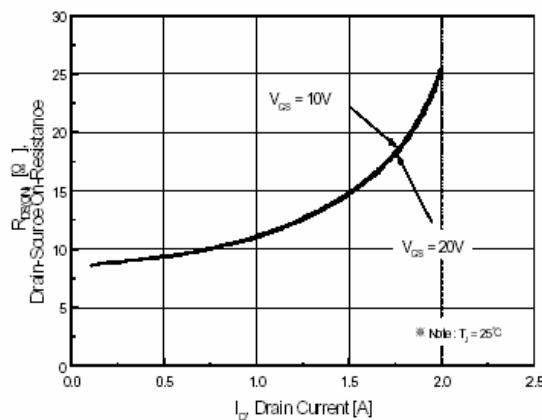


Figure 3. On-Resistance Variation vs  
Drain Current and Gate Voltage

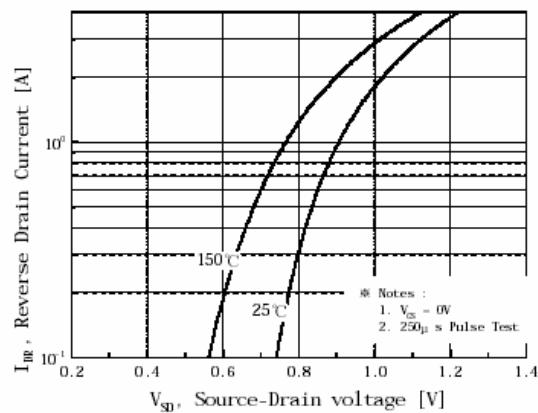


Figure 4. Body Diode Forward Voltage  
Variation with Source Current  
and Temperature

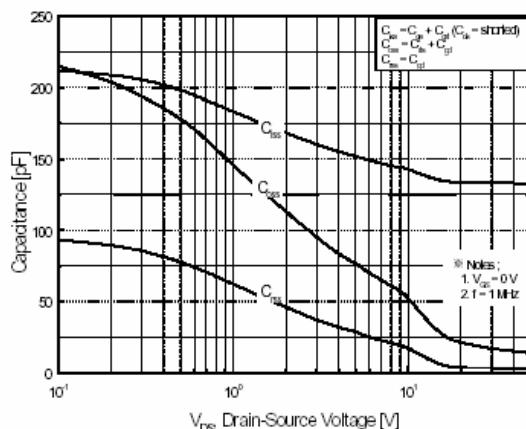


Figure 5. Capacitance Characteristics

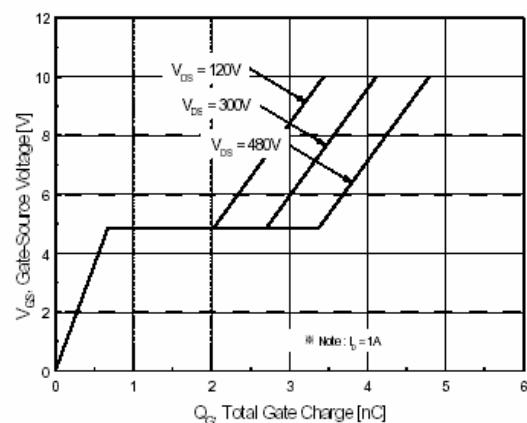


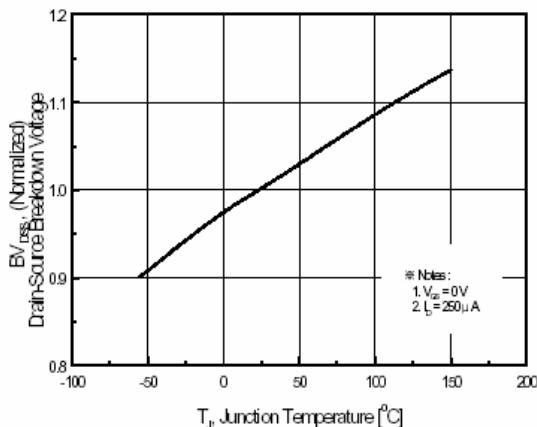
Figure 6. Gate Charge Characteristics



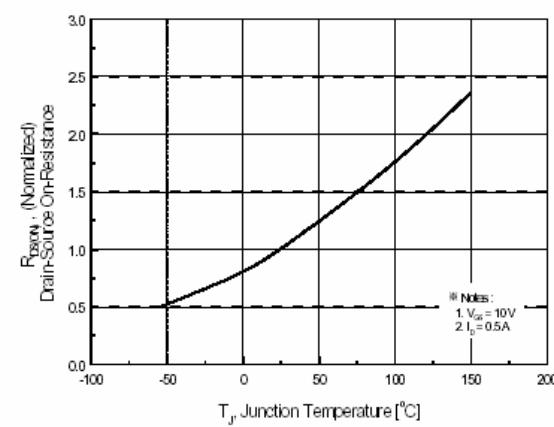
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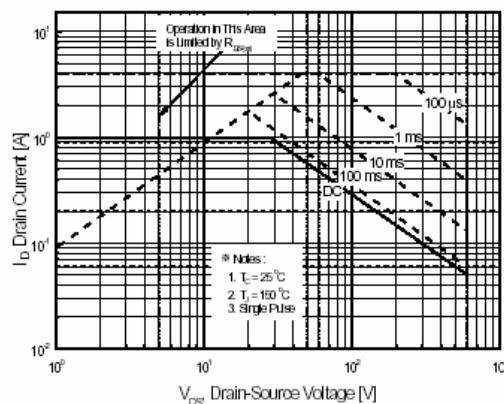
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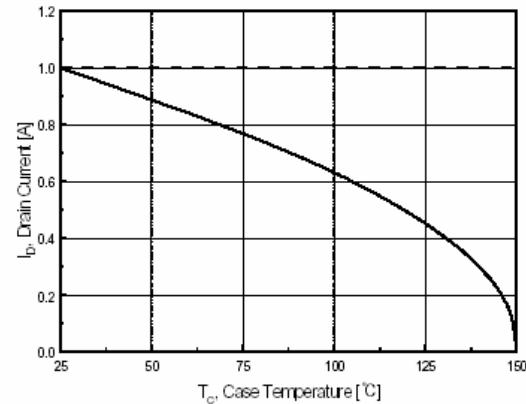
**Figure 7. Breakdown Voltage Variation vs Temperature**



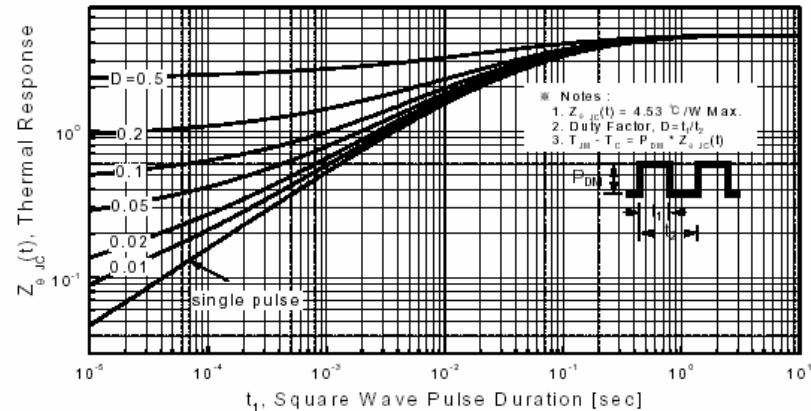
**Figure 8. On-Resistance Variation vs Temperature**



**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs Case Temperature**



**Figure 11. Transient Thermal Response Curve**

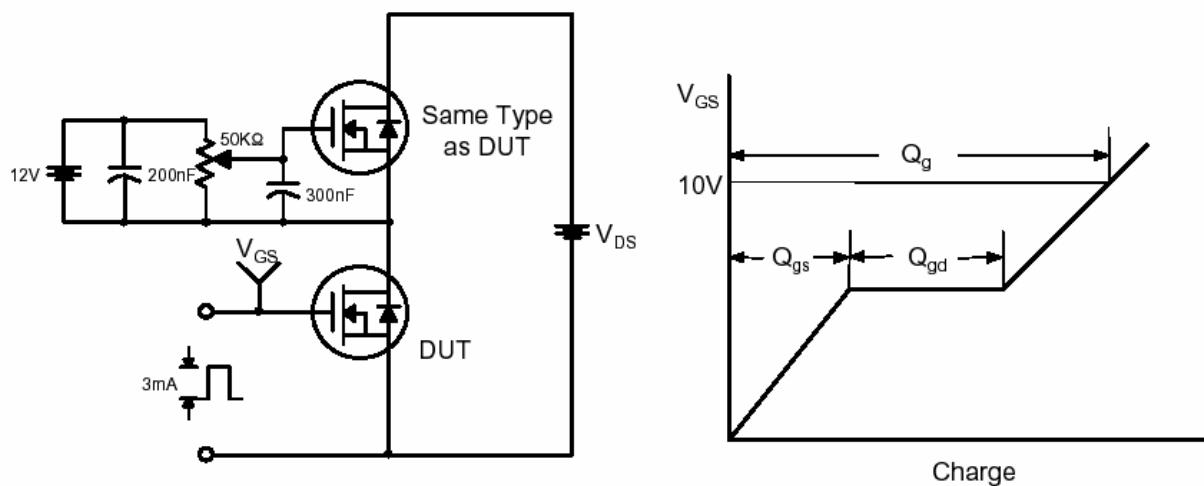


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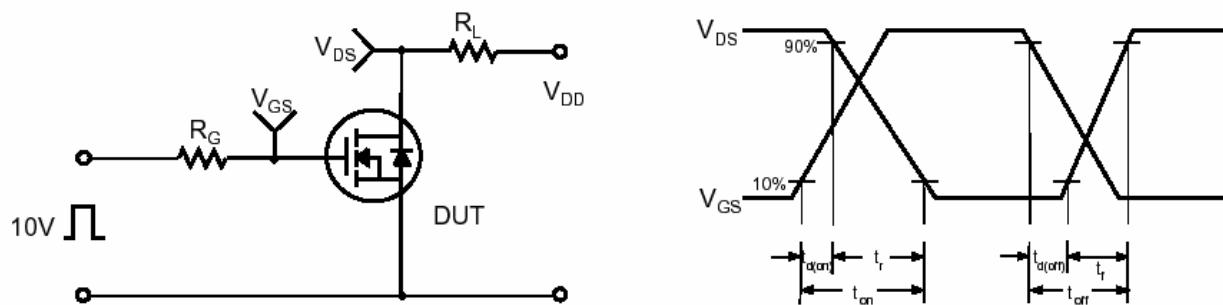
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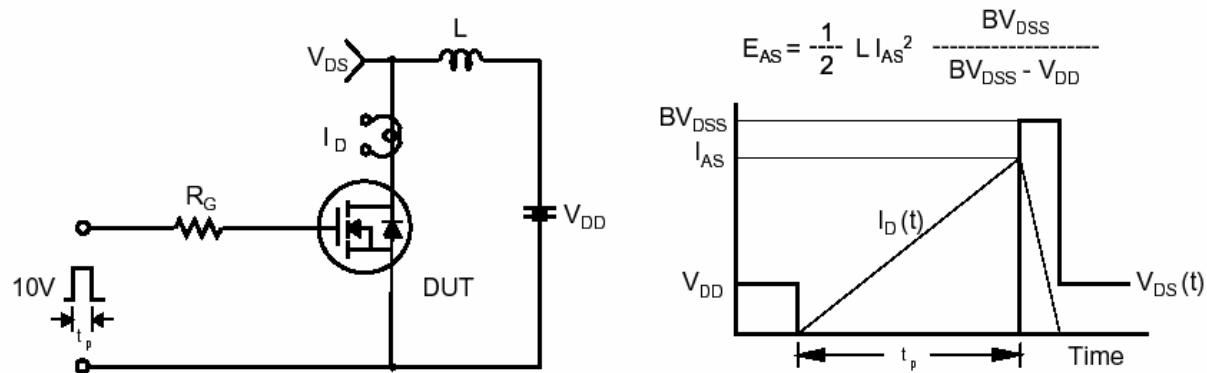
#### Gate Charge Test Circuit & Waveform



#### Resistive Switching Test Circuit & Waveforms



#### Unclamped Inductive Switching Test Circuit & Waveforms





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Peak Diode Recovery dv/dt Test Circuit & Waveforms

